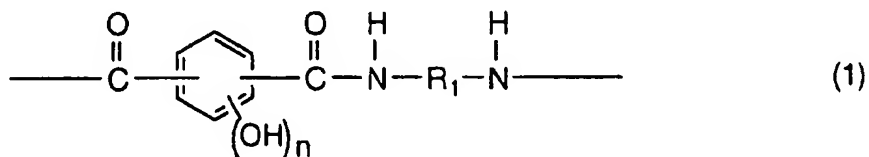


ABSTRACT

The present invention provides an adhesive aid composition having excellent adhesive strength to polyimide films without decreasing mechanical properties and being useful in the field of electric materials. An adhesive aid composition of the present invention contains a phenolic hydroxyl group-containing polyamide and a solvent as essential components. The phenolic hydroxyl group-containing polyamide preferably has a segment represented by formula (1):



(wherein R_1 represents a divalent aromatic group, and n represents an average number of substituents and is a positive number of 1 to 4). The adhesive aid composition of the present invention is suitably used for bonding polyimide films.